

ABSTRACT

A method for fabricating wafer-level chip scale packages is disclosed. A plurality of sacrificial photoresists with supporting surfaces in strip or bump configuration are formed on a surface of a wafer. Then, a negative photoresist layer is covered on the sacrificial photoresists. The negative photoresist layer is patterned in order to form a plurality of dielectric supporting bars on supporting surfaces of the sacrificial photoresists. Thereafter, a plurality of metal bars are formed on the dielectric supporting bars. Then the sacrificial photoresists are removed in order to form a plurality of pin terminals of the wafer-level chip scale packages for elastically surface-mounting to substrate or printed circuit board.